PCN Number: 201			1512	217000			PC	N Date:	12/18/2015
Title: Qualification of DI Technology		MOS	6 as an additio	onal Wafer F	ab Site op	tion	for select	devices in C021	
Cus	tomer	Contact:	PCN Manager		Dept:		Quality 9	Services	
Proposed 1 st Ship Date:			3/18/2016 Estimated Sample Availability:		-	Date provided at samp request.		vided at sample	
Change Type:									
Assembly Site			Assembly Process				Assembly	Materials	
Design			Electrical Specification				Mechanica	I Specification	
	Test S	ite		Packing/Shipping/Labeling		g		Test Proce	:SS
Wafer Bump Site			Wafer Bump Material				Wafer Bur	np Process	
			Wafer Fab Materials				Wafer Fab	Process	
				Part number	change				
	PCN Details								
Das	Description of Changes								

Description of Change:

This change notification is to announce the addition of DMOS6 as an additional Wafer Fab site option for the products listed in the product affected section of this document.

Current Wafer Fab Site	Process	Wafer Diameter
TSMC-F14	C021	300mm

Additional Fab Site	Process	Wafer Diameter
DMOS6	C021	300mm

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
TSMC-F14	T14	TWN	Tainan City

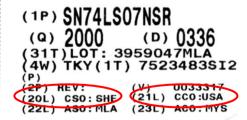
New Fab Site

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
DMOS6	DM6	USA	Dallas

Sample product shipping label (not actual product label)







Product Affected Group:						
CC2560ANPYFVR	CC2564NSRVMT	CC2564YFVR	CC2567YFVR			
CC2560ARVMR	CC2564NSYFVR	CC2564YFVT	CC2567YFVT			
CC2560ARVMT	CC2564NYFVR	CC2567NSYFVR	CC2568YFVR			
CC2560AYFVR	CC2564RVMR	CC2567RVMR	CC2569RVMR			
CC2560AYFVT	CC2564RVMT	CC2567RVMT	CC2569RVMT			
CC2564NSRVMR						

Qualification Report

Fab Transfer for C021.M Orca devices to DMOS6 for QFN and WCSP Packages Qualification Approved: 12/17/2015

Product Attributes

	Qual Device #1: BL6450QVRM	Qual Device #2: XCC2567YFVT	Supporting QBS#3: BL6450QVRM
Wafer Fab Site	DMOS6	DMOS6	TSMC-F14
Wafer Fab Process	C021.M	C021.M	C021.M
Die Size (mm)	2.957 X 3.294	2.957 X 3.294	2.957 X 3.294
Assembly Site	AMKOR P1	CLARK AT	AMKOR P1
Package Family	VQFN	WCSP	VQFN
Package Designator	RVM	YFV	RVM
Package Size (mils)	314.96 X 314.96	116.42 X 129.68	314.96 X 314.96
Pin Count	76	54	76
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0

⁻ QBS: Qual By Similarity

Qualification Results

Data Displayed as: Number of lots/Total sample size/Total failed

Туре	Test Name / Condition	Duration	Qual Device #1: BL6450QVRM	Qual Device #2: XCC2567YFVT	Supporting QBS #3: BL6450QVRM
THB	Temperature Humidity Bias 85C/85% RH	168, 600, 1000 Hours	2/154/0 & QBS to #3	3/86/0	2/154/0
UHAST	Unbiased HAST 110C/85% RH	264 Hours	3/231/0	N/A	N/A
UHAST	Unbiased HAST 130C/85% RH	96 Hours	N/A	3/230/0	N/A
TC	Temperature Cycle -55/125C	1000 Cycles	3/231/0	3/230/0	N/A
HTSL	High Temperature Storage Life 150C	1000 Hours	1/45/0 & QBS to #3	3/231/0	3/231/0
HTOL	High Temperature Operating Life 125C	1000 Hours	3/231/0	QBS to #1	N/A
ELFR	Early Life Failure Rate 125C	168 Hours	3/2400/0	QBS to #1	N/A
HBM	ESD - HBM	500V	1/3/0	1/3/0	N/A
CDM	ESD - CDM	250 V	1/3/0	1/3/0	N/A
LU	Latchup 90C	100mA	1/3/0	QBS to #1	N/A
MQ	Manufacturability	Per Site Specifications	Pass	Pass	N/A

⁻ Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com

⁻ Qual Device BL6450Q QFN is qualified at LEVEL3-260C

⁻ The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

⁻ The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours